

QMJU2.E182327 - Coatings for Use on Recognized Printed Wiring Boards - Component

Coatings for Use on Recognized Printed Wiring Boards - Component

GuangDong SQ UV Curing Materials Co.,Ltd

E182327

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Mtl Dsg	Coating Material			Flame Class	Laminate ANSI Type	Min Thk mm	Assembly Solder		Solder Limits	
	Color	Min Thk mic	Max Thk mic				Temp °C	Process Cycles	Process Temp °C	Time sec
Resist coatings for use on Recognized printd wiring boards. Furnished as: two component liquid										
PS-100/PS-100H	WT	15	35	V-0	Non-ANSI (#1)	(#1)	-	-	288	30
Resist coatings for use on Recognized printd wiring boards										
PSR-200/PSG-200 (ASP 1)	GN	10	40	V-0	FR-4.0	0.38	260	3	-	-
	BK	19	40	V-0	FR-4.0	0.38	260	3	-	-
UVC-II	GN	22	40	V-0	FR-1	1.45	-	-	260	10
UVC-II-G	GN	22	40	V-0	FR-4.0	0.38	-	-	288	20
	GN	8	30	V-0	FR-1	0.71	-	-	280	15
	GN	10	30	V-0	CEM-1	0.63	-	-	288	20

(#1) - Evaluation with Chin-Shi Electronic Materials Ltd (E206580) single-sided (SS) metal base laminate Grade CS-AL-88 (at 0.8mm metal base thickness with 0.060-0.165mm dielectric thickness).

(ASP 1) - Assembly Solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stess Assembly Simulation

Marking: Company name and model designation.

Last Updated on 2022-04-14

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